



Material Content Data Sheet



Sales Product Name		BTS5030-1EJA		Issued		5. December 2014			
MA#		MA001190342							
Package		PG-DSO-8-43		Weight*		84.45 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.062	2.44	2.44	24418	24418	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111		
	non noble metal	zinc	7440-66-6	0.038	0.04		445		
	non noble metal	iron	7439-89-6	0.752	0.89		8903		
wire	non noble metal	copper	7440-50-8	30.529	36.15	37.09	361504	370963	
	non noble metal	copper	7440-50-8	0.470	0.56	0.56	5562	5562	
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.11		1145	
	plastics	epoxy resin	-	4.447	5.27		52655		
	inorganic material	silicondioxide	60676-86-0	43.791	51.86	57.24	518542	572342	
leadfinish	non noble metal	tin	7440-31-5	0.814	0.96	0.96	9637	9637	
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8597	8597	
glue	plastics	epoxy resin	-	0.125	0.15		1484		
	noble metal	silver	7440-22-4	0.591	0.70	0.85	6997	8481	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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